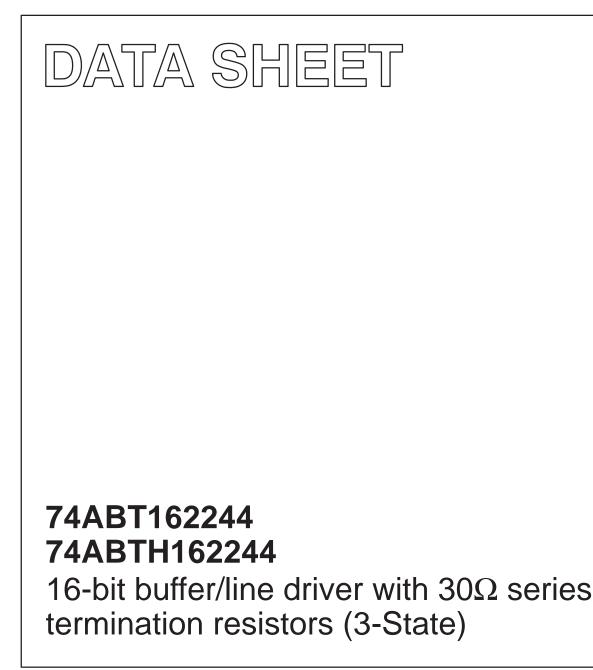
# INTEGRATED CIRCUITS



Product specification Supersedes data of 1998 Feb 25 IC23 Data Handbook

1998 Oct 22



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Semiconductors

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## 74ABT162244 74ABTH162244

48 20E

47

46 1A1 45

44

43

42

41

39

38

37

36

35 3A1

34

33

32 3A3

31

30

29

28

27 4A2

26 4A3

25 3OE

SA00013

1A0

GND

1A2

1A3

VCC

2A0 40

2A1

GND

2A2

2A3

3A0

GND

3A2

 $V_{CC}$ 

4A0

4A1

GND

**PIN CONFIGURATION** 

10F 1

1Y0

1Y1 3

1Y2

1Y3 6

VCC 7

2Y0 8

2Y1 9

GND 10

> 2Y2 11

> 2Y3 12

> 3Y0 13

> 3Y1 14

GND 15

> 3Y4 17

VCC

4Y0

4Y1 20

GND

4Y2 22

4Y3 23

40E 24

3Y2 16

18

19

21

GND 4

2

5

#### FEATURES

- 16-bit bus interface
- Multiple V<sub>CC</sub> and GND pins minimize switching noise
- Power-up 3-State
- 3-State buffers
- Output capability: +12 mA/-32mA
- Live insertion/extraction permitted
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Same part as 74ABT162244-1
- 74ABTH162244 incorporates bus hold data inputs which eliminate the need for external pull-up resistors to hold unused inputs
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs

### DESCRIPTION

The 74ABT162244 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed.

The 74ABT162244 device is a 16-bit buffer that is ideal for driving bus lines. The device features four Output Enables (10E, 20E, 30E, 40E), each controlling four of the 3-State outputs.

The 74ABT162244 is designed with  $30\Omega$  series resistance in both the upper and lower output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

The 74ABT162244 is the same as the 74ABT16244-1. The part number has been changed to reflect industry standards.

Two options are available, 74ABT162244 which does not have the bus hold feature and the 74ABTH162244 which incorporates the bus hold feature.

## QUICK REFERENCE DATA

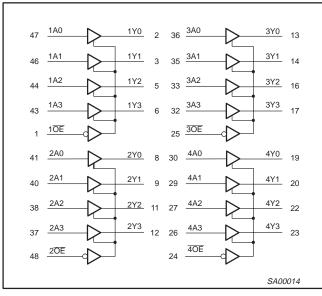
SYMBOL	PARAMETER	CONDITIONS T <sub>amb</sub> = 25°C; GND = 0V	TYPICAL	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nAx to nYx	$C_{L} = 50 pF; V_{CC} = 5V$	1.8 3.2	ns
C <sub>IN</sub>	Input capacitance	$V_{I} = 0V \text{ or } V_{CC}$	3	pF
C <sub>OUT</sub>	Output capacitance	$V_{O} = 0V \text{ or } V_{CC}$ ; 3-State	7	pF
I <sub>CCZ</sub>	Quiescent supply current	Outputs disabled; $V_{CC} = 5.5V$	500	μΑ
I <sub>CCL</sub>		Outputs Low; $V_{CC} = 5.5V$	10	mA

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABT162244 DL	BT162244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABT162244 DGG	BT162244 DGG	SOT362-1
48-Pin Plastic SSOP Type III	–40°C to +85°C	74ABTH162244 DL	BH162244 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH162244 DGG	BH162244 DGG	SOT362-1

## 74ABT162244 74ABTH162244

#### LOGIC SYMBOL



### **FUNCTION TABLE**

INP	OUTPUTS	
nOE	nAx	nYx
L	L	L
L	Н	н
н	Х	Z

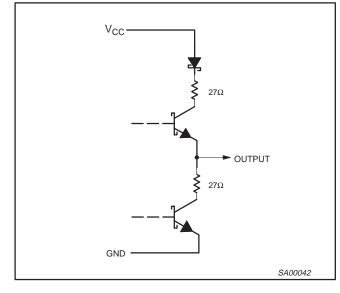
H = High voltage level

L = Low voltage level

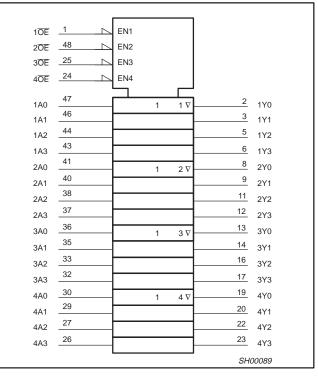
X = Don't care

Z = High impedance "off" state

### SCHEMATIC OF Y OUTPUTS



#### LOGIC SYMBOL (IEEE/IEC)



### **PIN DESCRIPTION**

PIN NUMBER	SYMBOL	NAME AND FUNCTION
47, 46, 44, 43 41, 40, 38, 37 36, 35, 33, 32 30, 29, 27, 26	1A0 – 1A3, 2A0 – 2A3, 3A0 – 3A3, 4A0 – 4A3	Data inputs
2, 3, 5, 6 8, 9, 11, 12 13, 14, 16, 17 19, 20, 22, 23	1Y0 – 1Y3, 2Y0 – 2Y3, 3Y0 – 3Y3, 4Y0 – 4Y3	Data outputs
1, 48 25, 24	1 <u>0E,</u> 2 <u>0E,</u> 3 <u>0E,</u> 4 <u>0E</u>	Output enables
4, 10, 15, 21 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V <sub>CC</sub>	Positive supply voltage

## 74ABT162244 74ABTH162244

#### ABSOLUTE MAXIMUM RATINGS<sup>1, 2</sup>

SYMBOL	PARAMETER	PARAMETER CONDITIONS		UNIT	
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V	
I <sub>IK</sub>	DC input diode current	V <sub>1</sub> < 0	-18	mA	
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V	
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA	
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	-0.5 to +5.5	V	
	DC output current	output in Low state	128		
IOUT		output in High state	-64	mA	
T <sub>stg</sub>	Storage temperature range		–65 to 150	°C	

NOTES:

1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

### **RECOMMENDED OPERATING CONDITIONS**

SYMBOL	PARAMETER	LIM	UNIT	
STMBOL	FARAMETER	Min	Max	UNIT
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

## 74ABT162244 74ABTH162244

### **DC ELECTRICAL CHARACTERISTICS**

					LIMITS					
SYMBOL	PARAMETER	TEST CONDITIONS		T <sub>amb</sub> = +25°C			T <sub>amb</sub> = −40°C to +85°C		דואט	
				Min	Тур	Мах	Min	Max	1	
V <sub>IK</sub>	Input clamp voltage	V <sub>CC</sub> = 4.5V; I <sub>IK</sub> = -18mA			-0.9	-1.2		-1.2	V	
		$V_{CC} = 4.5V; I_{OH} = -3mA; V_{I} = V_{II}$	_ or V <sub>IH</sub>	2.5	2.9		2.5		V	
V <sub>OH</sub>	High-level output voltage <sup>3</sup>	$V_{CC} = 5V; I_{OH} = -3mA; V_I = V_{IL}$	or V <sub>IH</sub>	3.0	3.4		3.0		V	
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} = V$	/ <sub>IL</sub> or V <sub>IH</sub>	2.0	2.4		2.0		V	
M		$V_{CC} = 4.5V; I_{OL} = 8mA; V_I = V_{IL}$	or V <sub>IH</sub>			0.65		0.65	V	
V <sub>OL</sub>	Low-level output voltage	$V_{CC} = 4.5V; I_{OL} = 12mA; V_I = V_{IL}$	or V <sub>IH</sub>			0.80		0.80	V	
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 5.5V; V <sub>I</sub> = GND or 5.5V			±0.01	±1.0		±1.0	μΑ	
		$V_{CC} = 5.5V; V_I = V_{CC}$ or GND	Control pins		±0.01	±1.0		±1.0	μA	
I <sub>I</sub>	Input leakage current 74ABTH162244 $V_{CC} = 5.5V; V_I = V_{CC}$ $V_{CC} = 5.5V; V_I = 0$ Data pins			0.01	1.0		1.0	μΑ		
			Data pins		-2.0	-3.0		-5.0	μΑ	
Bus Hold Current A Inputs <sup>4</sup>	$V_{CC} = 4.5V; V_{I} = 0.8V$		50			50				
	Bus Hold Current A Inputs <sup>4</sup> 74ABTH162244	$V_{CC} = 5.5V; V_1 = 2.0V$		-75			-75		μΑ	
		$V_{CC} = 5.5V; V_I = 0 \text{ to } 5.5V$		±500						
I <sub>OFF</sub>	Power-off leakage current	$V_{CC}$ = 0.0V; $V_O$ or $V_I \le 4.5 V$			±5.0	±100		±100	μΑ	
I <sub>PU/PD</sub>	Power-up/down 3-State output current	$V_{CC} = 2.0V$ ; $V_0 = 0.5V$ ; $V_1 = GNE$ $V_{OE} = Don't care$	D or V <sub>CC</sub> ;		±5.0	±50		±50	μA	
I <sub>OZH</sub>	3-State output High current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = V_{IL}$	or V <sub>IH</sub>		0.1	10		10	μΑ	
I <sub>OZL</sub>	3-State output Low current	$V_{CC} = 5.5V; V_{O} = 0.0V; V_{I} = V_{IL}$	or V <sub>IH</sub>		-0.1	-10		-10	μA	
I <sub>CEX</sub>	Output High leakage current	$V_{CC} = 5.5V; V_{O} = 5.5V; V_{I} = GNE$	D or V <sub>CC</sub>		5.0	50		50	μA	
Ι <sub>Ο</sub>	Output current <sup>1</sup>	$V_{CC} = 5.5V; V_{O} = 2.5V$		-50	-100	-180	-50	-180	mA	
I <sub>CCH</sub>		$V_{CC}$ = 5.5V; Outputs High, $V_{I}$ = 0	OND or V <sub>CC</sub>		0.50	1.0		1.0	mA	
I <sub>CCL</sub>	Quiescent supply current <sup>3</sup>	$V_{CC}$ = 5.5V; Outputs Low, $V_{I}$ = G	ND or V <sub>CC</sub>		10	19		19	mA	
I <sub>CCZ</sub>		$V_{CC}$ = 5.5V; Outputs 3-State; V <sub>I</sub> = GND or V <sub>CC</sub>			0.50	1.0		1.0	mA	
		Outputs enabled, one data input other inputs at $V_{CC}$ or GND; $V_{CC}$	at 3.4V, = 5.5V		100	250		250	μA	
$\Delta I_{CC}$	Additional supply current per input pin <sup>2, 3</sup>	Outputs disabled, one data input at 3.4V, other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = $5.5V$			100	250		250	μA	
		Control pins, outputs disabled, one enable input at 3.4V, other inputs at $V_{CC}$ or GND; $V_{CC} = 5.5V$			100	250		250	μA	

NOTES:

1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input at 3.4V.
This data sheet limit may vary among suppliers.

4. This is the bus hold overdrive current required to force the input to the opposite logic state.

## 74ABT162244 74ABTH162244

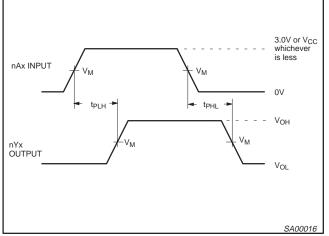
#### **AC CHARACTERISTICS**

GND = 0V;  $t_R = t_F$  = 2.5ns;  $C_L$  = 50pF,  $R_L$  = 500 $\Omega$ 

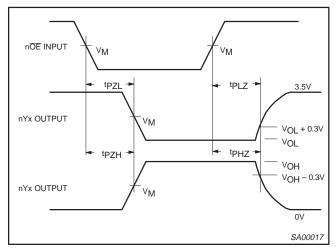
					LIMITS			
SYMBOL	PARAMETER	WAVEFORM		T <sub>amb</sub> = +25°C V <sub>CC</sub> = +5.0V	:	$T_{amb} = -40^{\circ}$ $V_{CC} = +5.$	℃ to +85°C 0V ±0.5V	UNIT
			Min	Тур	Мах	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay nAx to nYx	1	1.0 1.6	1.8 3.2	2.4 4.0	1.0 1.6	2.7 4.4	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to High and Low level	2	1.2 2.6	2.7 5.0	3.5 6.2	1.2 2.6	4.3 7.3	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from High and Low level	2	1.5 1.3	3.0 2.6	3.8 3.3	1.5 1.3	4.5 4.6	ns

#### AC WAVEFORMS

 $V_{M}$  = 1.5V,  $V_{IN}$  = GND to 3.0V



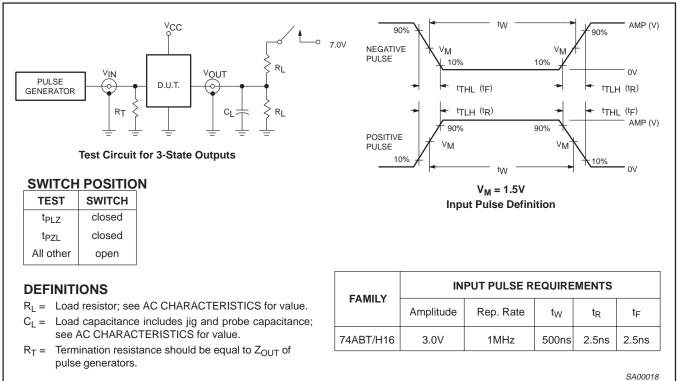
Waveform 1. Input (An) to Output (Yn) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

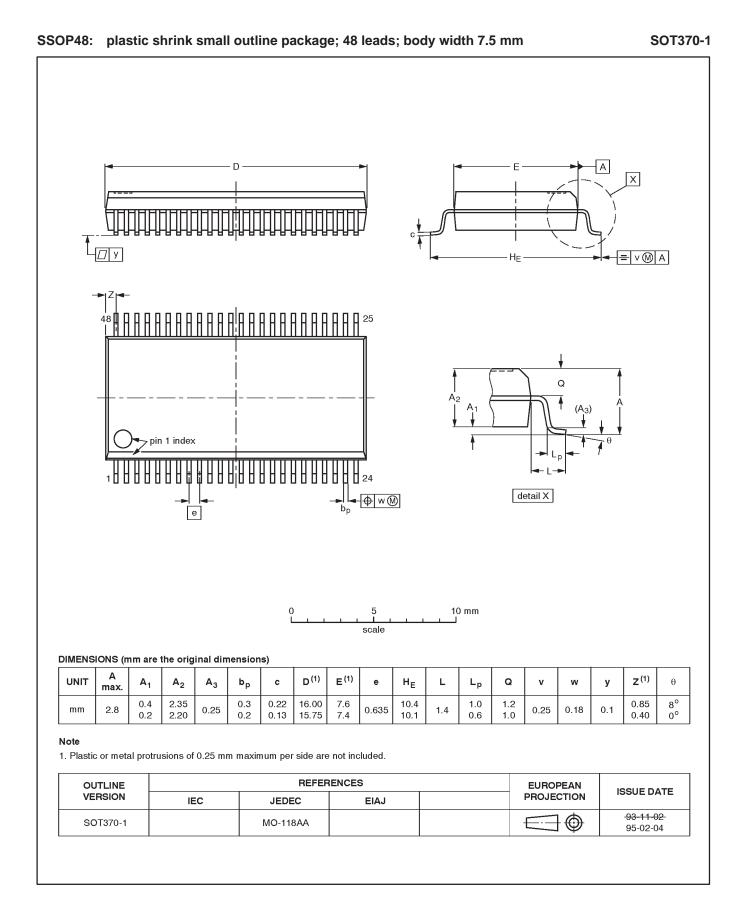
## 74ABT162244 74ABTH162244

### **TEST CIRCUIT AND WAVEFORMS**

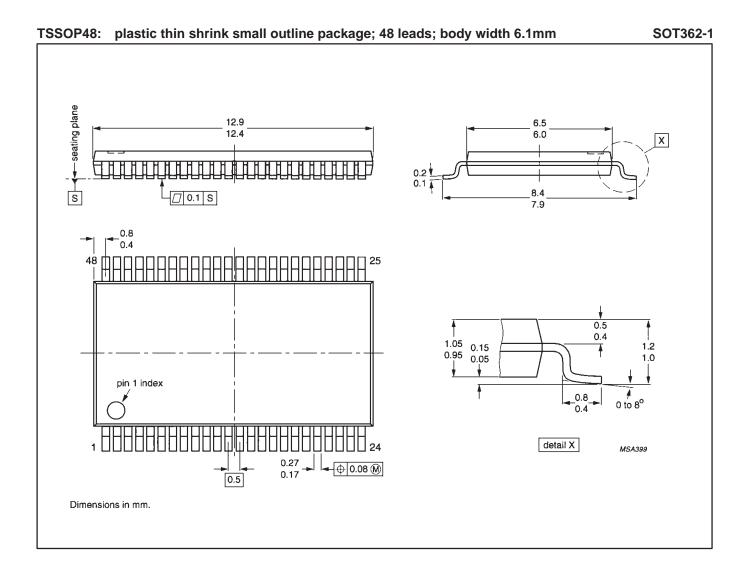


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## 74ABT162244 74ABTH162244



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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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